

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT APPLICATION**

Appl. No.: 10/695,026	Confirmation No.: 5704
Applicant: Sunil Thomas	
Filed: October 28, 2003	
TC/AU: 2813	
Examiner: Jack S. J. Chen	
Docket: TI-29525.1A	
Cust. No.: 23494	
Title: Flip-Chip Assembly of Protected Micromechanical Devices	

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

Supplement to Previous Amendments under 37 CFR § 1.111

Dear Sir:

In response to the non-final Office Action mailed September 21st, 2006 in connection with the above identified application, Applicant respectfully submits the following amendments and remarks:

Amendments to the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.